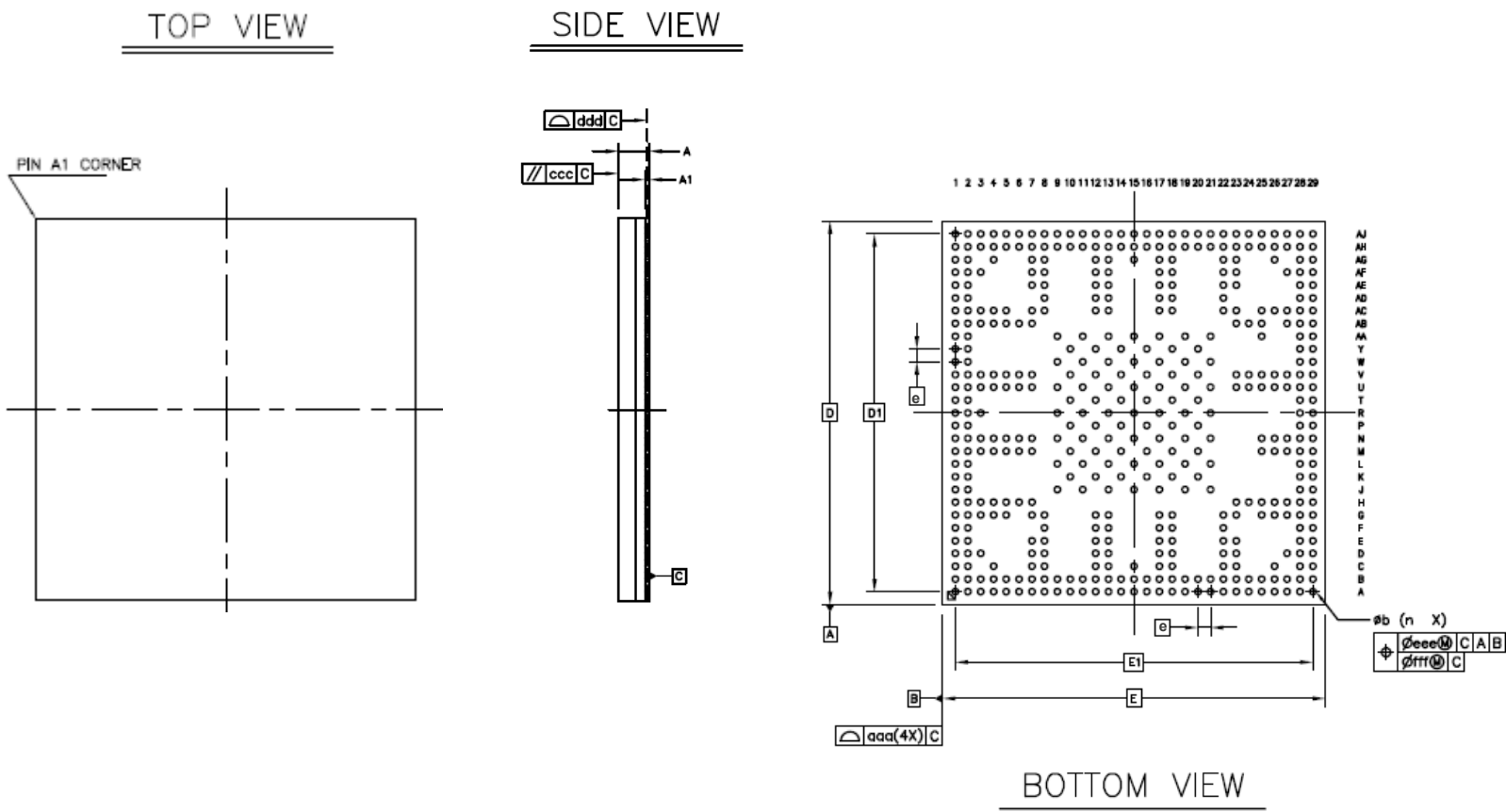


RZ/V2L

PACKAGE OUTLINE DRAWING

APR 2022 REV1.00
MPU PRODUCT DEPARTMENT
ENTERPRISE INFRASTRUCTURE BUSINESS DIVISION
RENESAS ELECTRONICS CORPORATION

Package outline (15mm body) RZ/V2L



			Common Dimensions		
Parameter		Symbol	MIN	NOM	MAX
Body size	X	E	15		
	Y	D	15		
Ball pitch		e	0.500		
Total Thickness		A	1.100	1.250	1.400
Stand Off		A1	0.110	-	0.210
Ball Width		b	0.200	-	0.300
Pakeage Edge Tolerance		aaa	0.150		
Mold Parallelism		ccc	0.200		
Coplanarity		ddd	0.080		
Ball offset (Package)		eee	0.150		
Ball offset (Ball)		fff	0.080		
Ball count		n	456		
Edge Ball Center to Center	X	E1	14.000		
	Y	D1	14.000		

REVISION HISTORY

Rev.	Date	Description
1.00	Apr. 2022	Initial release

[Renesas.com](https://www.renesas.com)